



Material Content Data Sheet



Sales Product Name		IPB180N03S4L-H0		Issued		25. September 2017		
MA#		MA000671990						
Package		PG-TO263-7-3		Weight*		1539.70 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	8.901	0.58	0.58	5781	5781
leadframe	non noble metal	iron	7439-89-6	0.803	0.05		521	
	inorganic material	phosphorus	7723-14-0	0.241	0.02		156	
	non noble metal	copper	7440-50-8	801.714	52.05	52.12	520694	521372
wire	non noble metal	aluminium	7429-90-5	129.475	8.41	8.41	84091	84091
encapsulation	organic material	carbon black	1333-86-4	7.105	0.46		4615	
	plastics	epoxy resin	-	78.160	5.08		50763	
	inorganic material	silicondioxide	60676-86-0	388.430	25.23	30.77	252277	307655
leadfinish	non noble metal	tin	7440-31-5	12.317	0.80	0.80	7999	7999
plating	non noble metal	nickel	7440-02-0	0.269	0.02		175	
	inorganic material	phosphorus	7723-14-0	0.001	0.00	0.02	1	175
solder	noble metal	silver	7440-22-4	0.148	0.01		96	
	non noble metal	tin	7440-31-5	0.119	0.01		77	
	non noble metal	lead	7439-92-1	5.670	0.37	0.39	3683	3856
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		69	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.210	6.90	6.91	68981	69071
*deviation	< 10%				Sum in total:	100.00		1000000

Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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